

3 mm (T1) MULTILED[®], Non Diffused

LSG 3331



Besondere Merkmale

- **Gehäusetypp:** nicht eingefärbtes, klares 3 mm (T1) Gehäuse
- **Besonderheit des Bauteils:** antiparallel geschaltete Chips; Lötspieße mit Aufsetzebene
- **Wellenlänge:** 628 nm (super-rot), 570 nm (grün)
- **Abstrahlwinkel:** 40°
- **Technologie:** GaAlP
- **optischer Wirkungsgrad:** 1,5 lm/W (super-rot), 2,5 lm/W (grün)
- **Gruppierungsparameter:** Lichtstärke
- **Lötmethode:** Wellenlöten (TTW)
- **Verpackung:** Schüttgut, gegurtet lieferbar

Anwendungen

- optischer Indikator
- Hinterleuchtung (LCD, Schalter, Tasten, Displays, Werbebeleuchtung, Allgemeinbeleuchtung)
- Innenbeleuchtung im Automobilbereich (z. B. Tastenhinterleuchtung, u. ä.)

Features

- **package:** colorless, clear 3 mm (T1) package
- **feature of the device:** anti-parallel chips; solder leads with stand-off
- **wavelength:** 628 nm (super-red), 570 nm (green)
- **viewing angle:** 40°
- **technology:** GaAlP
- **optical efficiency:** 1.5 lm/W (super-red), 2.5 lm/W (green)
- **grouping parameter:** luminous intensity
- **soldering methods:** TTW soldering
- **Packing:** bulk, available taped on reel

Applications

- optical indicators
- backlighting (LCD, switches, keys, displays, illuminated advertising, general lighting)
- interior automotive lighting (e.g. key backlighting, etc.)

Typ Type	Emissionsfarbe Color of Emission	Gehäusefarbe Color of Package	Lichtstärke Luminous Intensity $I_F = 10 \text{ mA}$ $I_V \text{ (mcd)}$	Bestellnummer Ordering Code
LSG 3331-JO	super-red / green	colorless clear	≥ 4.5 (18 typ.)	Q62703-Q2296

Streuung der Lichtstärke in einer Verpackungseinheit $I_{V \text{ max}} / I_{V \text{ min}} \leq 2$ ¹⁾.

Streuung der Lichtstärke in einer LED $I_{V \text{ max}} / I_{V \text{ min}} \leq 3$.

¹⁾ Bei MULTILED® bestimmt die Helligkeit des jeweils dunkleren Chips in einem Gehäuse die Helligkeitsgruppe der LED.

Luminous intensity ratio in one packaging unit $I_{V \text{ max}} / I_{V \text{ min}} \leq 2$ ¹⁾.

Luminous intensity ratio in one LED $I_{V \text{ max}} / I_{V \text{ min}} \leq 3$.

¹⁾ In case of MULTILED®, the brightness of the darker chip in one package unit determines the brightness group of the LED.

Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von ± 11 % ermittelt.

Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of ± 11 %.

Anm.: Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe oder mindestens zwei Einzelgruppen.

In einer Verpackungseinheit / Gurt ist immer nur eine Helligkeitsgruppe enthalten.

Die technologiebedingte Helligkeits-Streuung der heutigen LED-Herstellprozesse über einen längeren Fertigungszeitraum (Halbleitermaterial - Chipherstellung - Montageprozess) erlaubt keine Zusage einer einzelnen Helligkeitsgruppe. Daher müssen mindestens zwei Helligkeitsgruppen vorgesehen werden!

Note: The standard shipping format for serial types includes a lower or upper family group or at least two individual groups.

No packing unit / tape ever contains more than one luminous intensity group.

Luminosity variations caused by the technology used in current LED manufacturing processes over a protracted manufacturing period (semiconductor material - chip fabrication - assembly process) mean that it is not possible to assign LEDs to a single luminous intensity group. For this reason at least two luminous intensity groups must be provided!

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebstemperatur Operating temperature range	T_{op}	- 55 ... + 100	°C
Lagertemperatur Storage temperature range	T_{stg}	- 55 ... + 100	°C
Sperrschichttemperatur Junction temperature	T_j	+ 100	°C
Durchlassstrom Forward current	I_F	40	mA
Stoßstrom Surge current $t \leq 10 \mu s, D = 0.005$	I_{FM}	0.5	A
Leistungsaufnahme Power consumption $T_A \leq 25 \text{ °C}$	P_{tot}	130	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient	$R_{th JA}$	400	K/W
Sperrschicht/Löt看 Junction/solder point Montage auf PC-Board FR 4 (Padgröße $\geq 16 \text{ mm}^2$) mounted on PC board FR 4 (pad size $\geq 16 \text{ mm}^2$) Minimale Beinchenlänge Minimum lead length	$R_{th JS}$	180	K/W

Bezeichnung Parameter	Symbol Symbol	Werte Values		Einheit Unit
		LS	LG	
Wellenlänge des emittierten Lichtes (typ.) Wavelength at peak emission $I_F = 10 \text{ mA}$	λ_{peak}	635	572	nm
Dominantwellenlänge ¹⁾ (typ.) Dominant wavelength $I_F = 10 \text{ mA}$	λ_{dom}	628	570	nm
Spektrale Bandbreite bei 50 % $I_{\text{rel max}}$ (typ.) Spectral bandwidth at 50 % $I_{\text{rel max}}$ $I_F = 10 \text{ mA}$	$\Delta\lambda$	45	25	nm
Abstrahlwinkel bei 50 % I_V (Vollwinkel) (typ.) Viewing angle at 50 % I_V	2ϕ	40	40	Grad deg.
Durchlassspannung ²⁾ (typ.) Forward voltage (max.) $I_F = 10 \text{ mA}$	V_F V_F	2.0 2.4	2.0 2.4	V V
Temperaturkoeffizient von λ_{peak} (typ.) Temperature coefficient of λ_{peak} $I_F = 10 \text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{peak}}}$	0.11	0.11	nm/K
Temperaturkoeffizient von λ_{dom} (typ.) Temperature coefficient of λ_{dom} $I_F = 10 \text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{dom}}}$	0.07	0.07	nm/K
Temperaturkoeffizient von V_F (typ.) Temperature coefficient of V_F $I_F = 10 \text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	TC_V	- 1.9	- 1.4	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 10 \text{ mA}$	η_{opt}	1.5	2.5	lm/W

¹⁾ Wellenlängen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 1 \text{ nm}$ ermittelt.
Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of $\pm 1 \text{ nm}$.

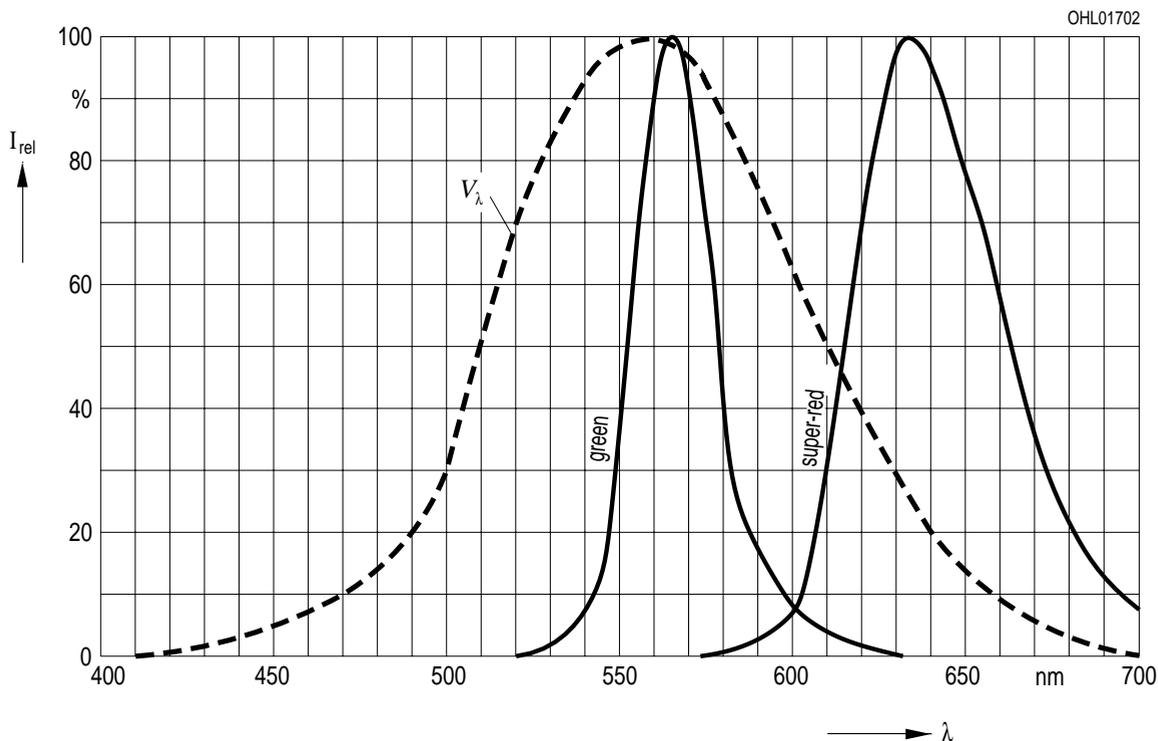
²⁾ Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von $\pm 0,1 \text{ V}$ ermittelt.
Voltages are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.1 \text{ V}$.

Relative spektrale Emission $I_{rel} = f(\lambda)$, $T_A = 25\text{ °C}$, $I_F = 10\text{ mA}$

Relative Spectral Emission

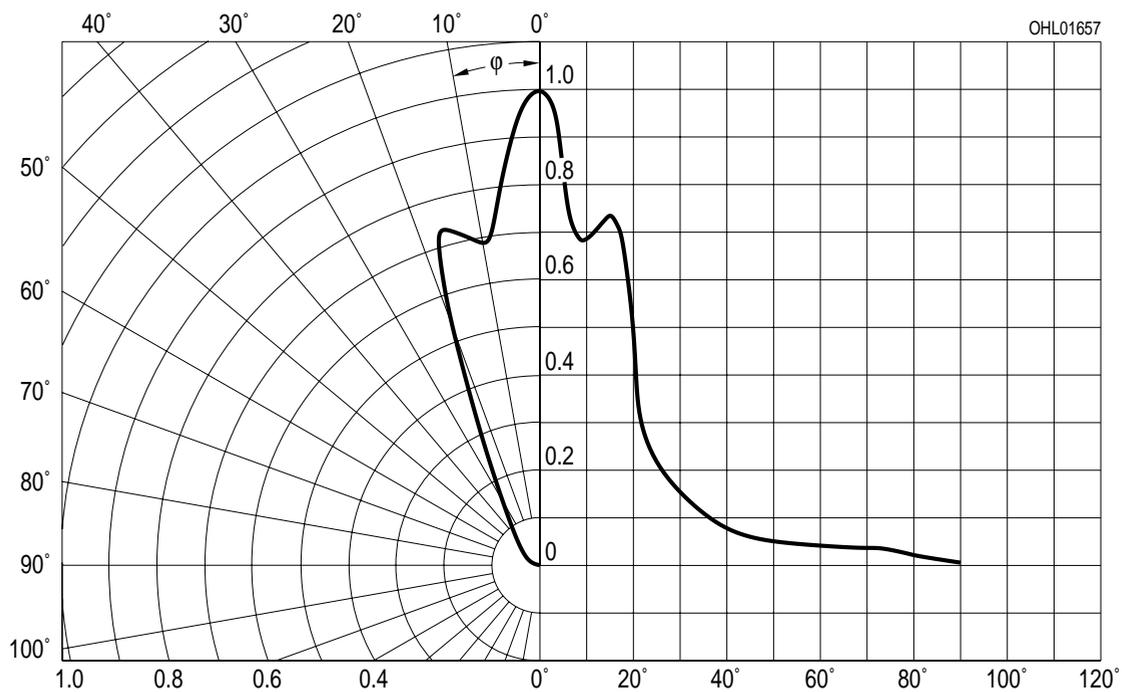
$V(\lambda)$ = spektrale Augenempfindlichkeit

Standard eye response curve



Abstrahlcharakteristik $I_{rel} = f(\varphi)$

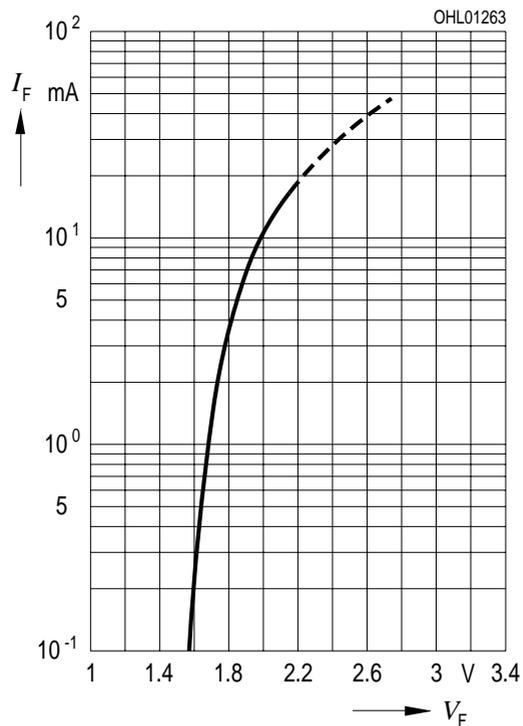
Radiation Characteristic



Durchlassstrom $I_F = f(V_F)$

Forward Current

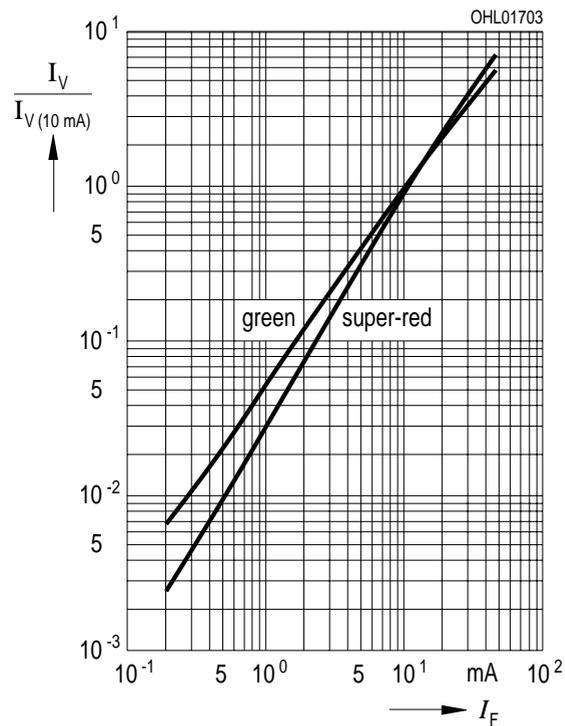
$T_A = 25\text{ °C}$



Relative Lichtstärke $I_V/I_{V(10\text{ mA})} = f(I_F)$

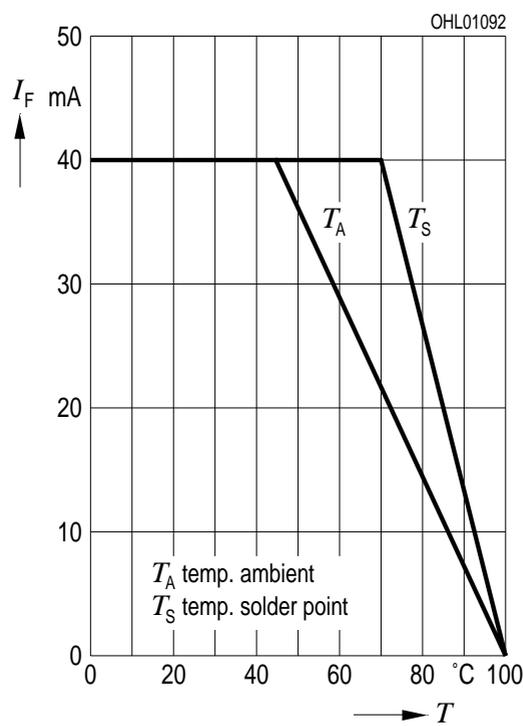
Relative Luminous Intensity

$T_A = 25\text{ °C}$



Maximal zulässiger Durchlassstrom $I_F = f(T)$

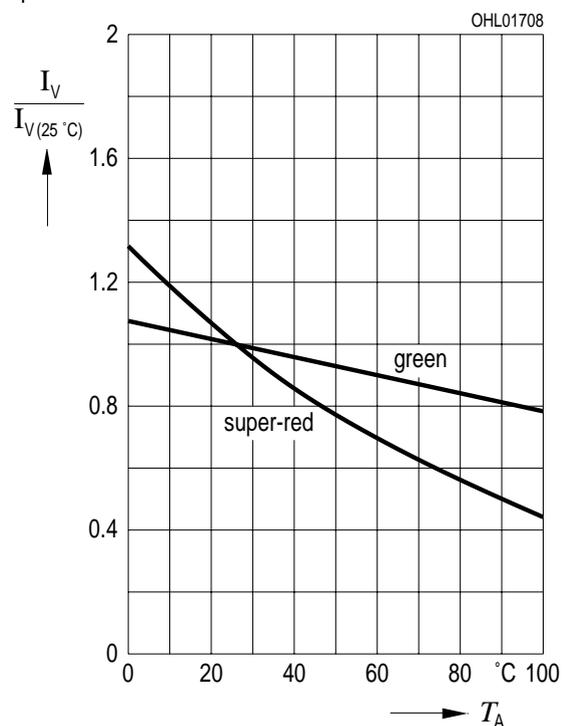
Max. Permissible Forward Current



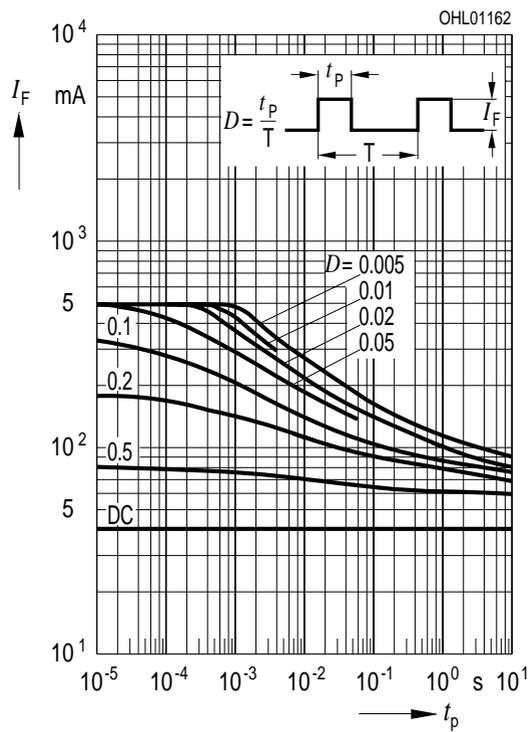
Relative Lichtstärke $I_V/I_{V(25\text{ °C})} = f(T_A)$

Relative Luminous Intensity

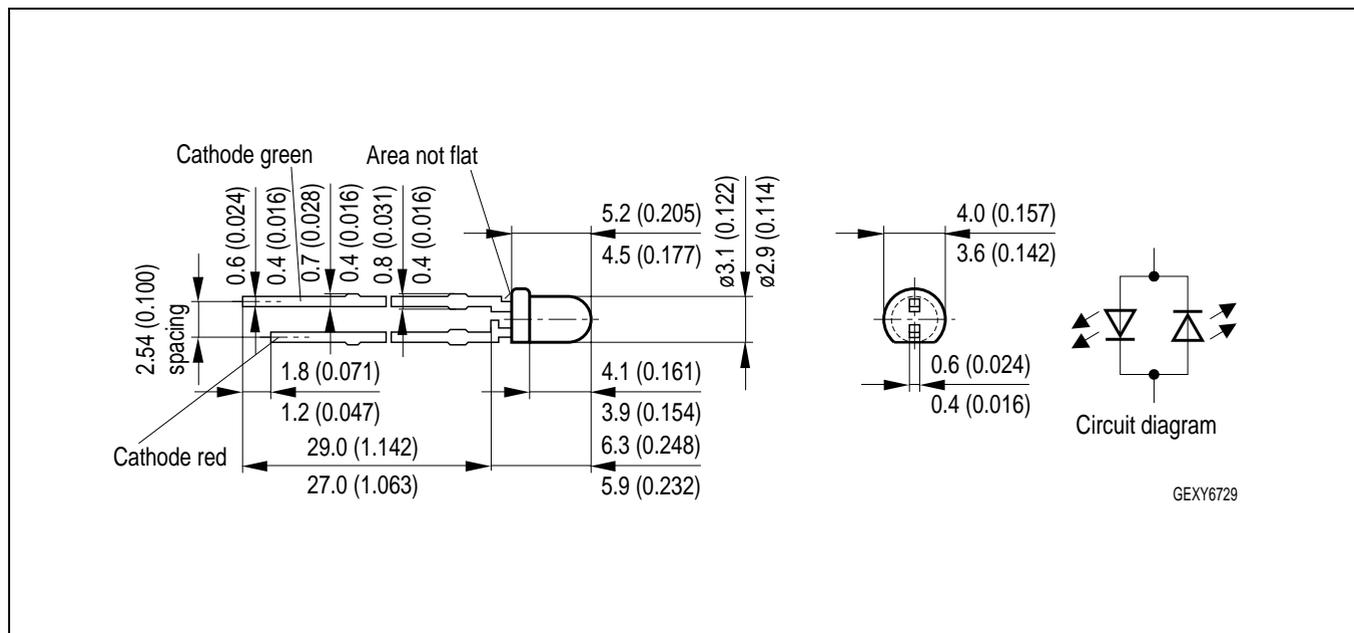
$I_F = 10\text{ mA}$



Zulässige Impulsbelastbarkeit $I_F = f(t_p)$
Permissible Pulse Handling Capability
 Duty cycle $D =$ parameter, $T_A = 25\text{ °C}$



**Maßzeichnung
Package Outlines**

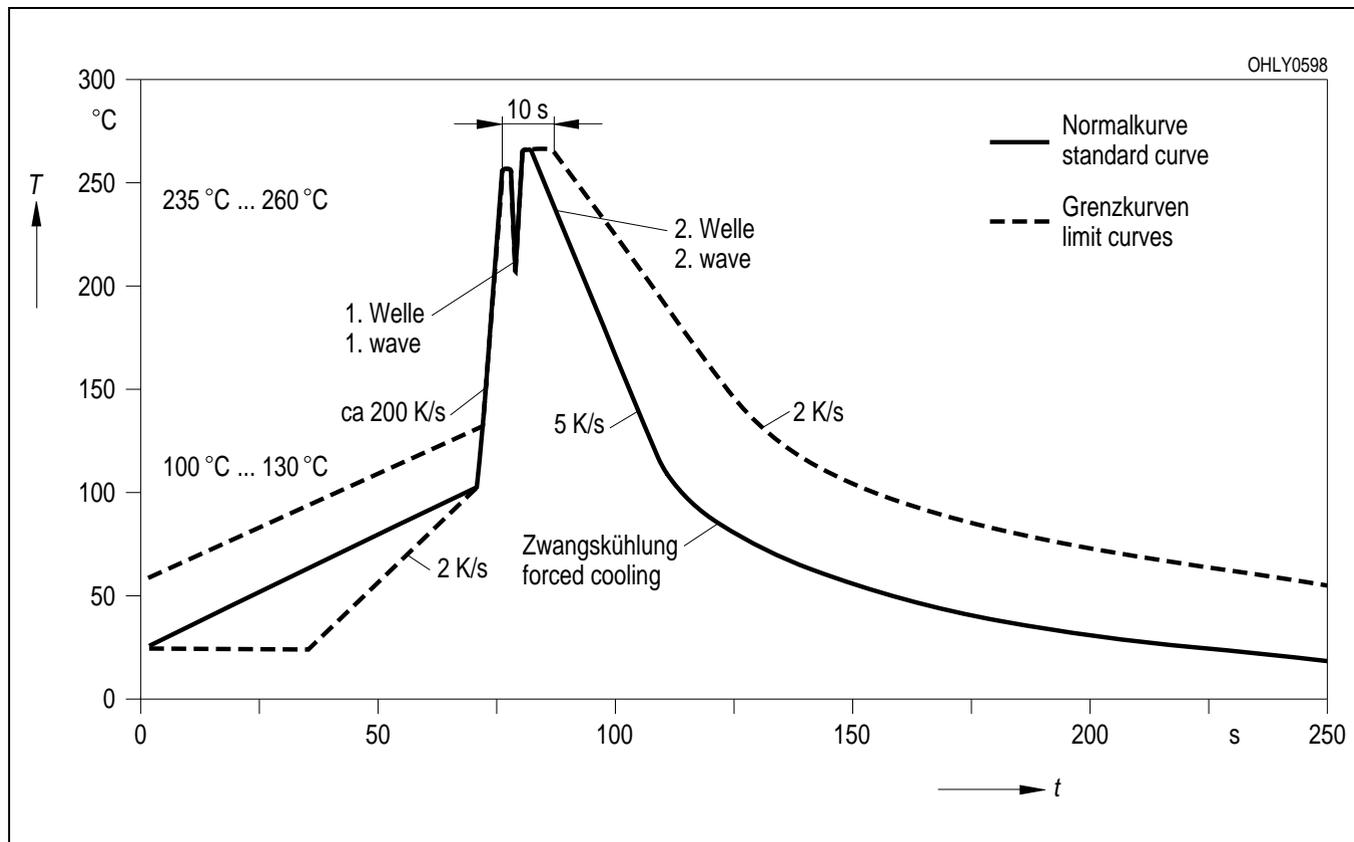


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

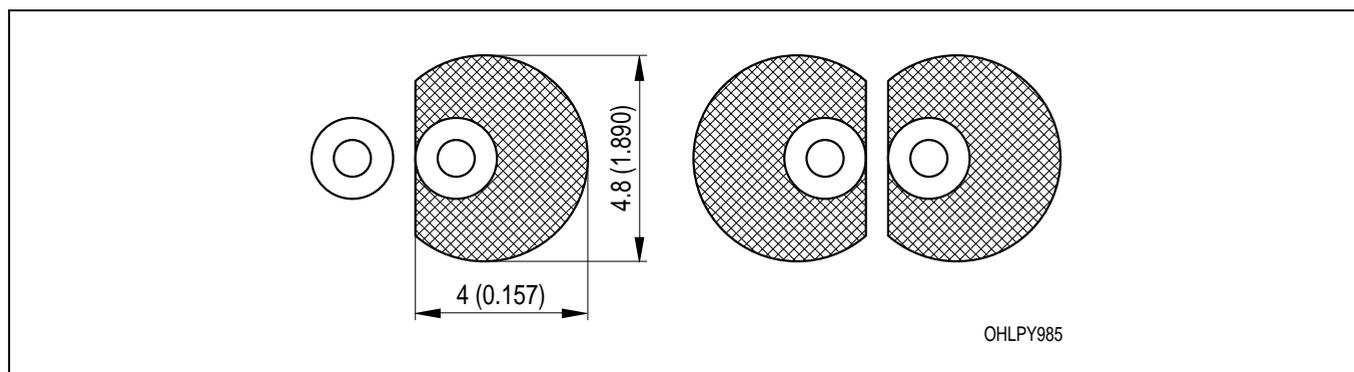
- Kathodenkennung:** grün: längerer Lötspieß
rot: kürzerer Lötspieß
- Cathode mark:** green: long solder lead
red: short solder lead
- Gewicht / Approx. weight:** 0.15 g

Lötbedingungen
Soldering Conditions

Wellenlöten (TTW) (nach CECC 00802)
TTW Soldering (acc. to CECC 00802)



Empfohlenes Lötpad design Wellenlöten (TTW)
Recommended Solder Pad TTW Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2001-03-12

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Page	Subjects (major changes since last revision)

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Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose! Critical components ¹ may only be used in life-support devices or systems ² with the express written approval of OSRAM OS.

¹ A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

² Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.